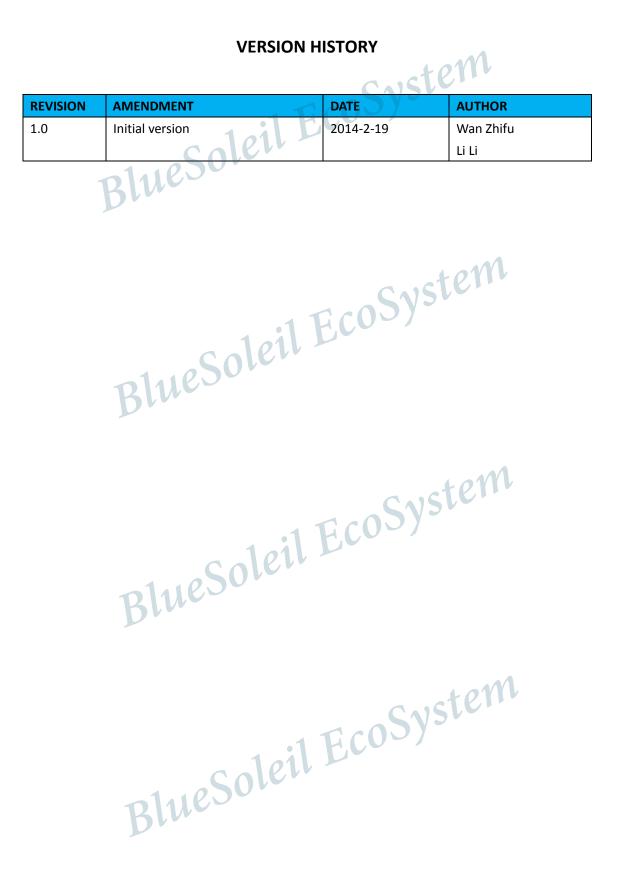


BlueSoleil EcoSystem Blues leil i410e-S Datasheet

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BlueSoleil EcoSystem







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BlueSoleil EcoSystem

BlueSoleil EcoSystem

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BlueS leil i410e-S

DESCRIPTION

BlueSoleil i410e-S is a Bluetooth 4.0 single-mode module. It provides a Bluetooth Low Energy fully compliant system for data communication with IVT BlueSoleil stack. It allows your target devices to send and receive data via Bluetooth 4.0 without connecting a serial cable to your computer.

By default, i410e-S module is equipped with powerful and easy-to-use BlueSoleil firmware. It's easy-to-use and completely encapsulated. BlueSoleil enables users to access Bluetooth functionality with simple ASCII commands delivered to the module over serial interface it's just like a Bluetooth modem.

Therefore, BlueSoleil i410e-S provides an BlueSoleil EcoSystem ideal solution for developers who want to integrate Bluetooth wireless technology into their design.

FEATURES

- Fully Qualified Bluetooth system v4.0 •
- Low energy
- ٠ Support Master or Slave roles
- Integrated layout antenna
- Industrial temperature range from -40^oC • $to + 85^{\circ}C$
- **RoHS** Compliant

APPLICATIONS

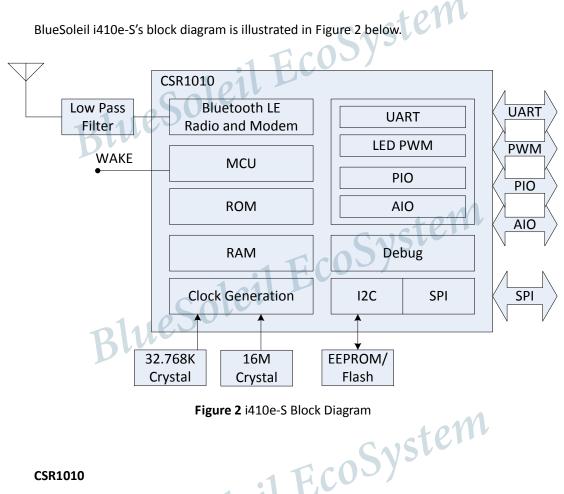
- Cable replacement
- Sports and fitness
- Healthcare
- Home entertainment
- Office and mobile accessories
- Automotive
- Commercial
- Watches
- Human interface devices

Figure 1 BlueSoleil i410e-S

BlueSoleil EcoSystem



1 Block Diagram



CSR1010

CSR1010 is a single chip Bluetooth 4.0 solution which implements the Bluetooth radio transceiver and also an on chip microcontroller. CSR1010 implements Bluetooth 4.0 and it can deliver data rates up to 3 Mbps.

The microcontroller (MCU) on CSR1010 acts as interrupt controller and event timer run the BlueSoleil stack and control the radio and host interfaces. A 16-bit RISC microcontroller is used for low power consumption and efficient use of memory.

CSR1010 has 64Kbytes of on-chip RAM. It supports the RISC MCU and is shared between the ring buffers used to hold data for each active connection and the general-purpose memory solei required by the BlueSoleil stack.

Crystal

The crystal oscillates include 16MHz and 32.768 KHz. 16MHz is external reference clock source. 32.768 KHz is used during deep sleep and in other low-power modes.

EEPROM/Flash



Flash /EEPROM is used for storing the Bluetooth protocol stack, profile and applications.

Low Pass Filter

EcoSystem The filter is a band pass filter (ISM band).

Antenna

The antenna is meander PCB antenna.

Synchronous Serial Interface

This is a synchronous serial port interface (SPI) for interfacing with other digital devices. The SPI port can be used for system debugging. It can also be used for programming the Flash memory.

UART

This is a standard Universal Asynchronous Receiver Transmitter (UART) interface for I Eco communicating with other serial devices.

Programmable I/O

I410e-S has five digital programmable I/O terminals controlled by firmware running on the device.

AIO

vstem i410e-S has three general-purpose analogue interface pins, AIO[2:0].

PWM

i410e-S contains a PWM module that works in sleep modes

WAKE

Wake up input. It wakes i410e-S from sleep mode.

2.1Absolute Maximum Ratings EcoSystem

The module should not continuously run under extreme conditions. The absolute maximum ratings are summarized in Table 1 below. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability and cause permanent damage to the device.

Table 1 Absolute Maximum Ratings



Rating	Min	Max	Unit			
Storage temperature	-40	85	°C			
Battery (VDD_BAT)operation	1.8	3.6	V			
I/O supply voltage	-0.4	3.6	V			
Other terminal voltages	VSS-0.4	VDD+0.4	V			
Other terminal voltages VSS-0.4 VDD+0.4						

2.2Recommended Operating Conditions

Recommended operating conditions are summarized in Table 2 below.

Table 2 Recommended Operating Conditions

	Min	Тур	Max	Unit
Operating temperature	-30	20	85	°C
Battery(VDD_BAT) Operation	1.8	TCOS	3.6	V
I/O supply	1.2		3.6	V
voltage(VDD_PADS)				
Blue				

2.3Input/output Terminal Characteristics

2.3.1 Switch-mode Regulator

2.3.1 Switch-mode Reg	gulator	F.coS	ystem	
Table 3 Switch-mode Regulator	Min	Тур.	Max	Unit
Switch-mode Regulator	<u> </u>			
input voltage	1.8	-	3.6	V
Output voltage	0.65	1.35	1.35	V
Temperature coefficient	-200	-	200	ppm/ ⁰ C
Normal Operation			Lom	
Output noise, Frequency range 100Hz to 100KHz	-	TCOS	S _{0.4}	mV rms
Setting time, setting to within 10% of final value	solei	Ecc	30	μs
Output current(I _{max})	301	-	50	mA
Quiescent current(excluding load, I _{load} <1mA)	-	-	20	μΑ
Ultra Low-power Mode				



Output current(I _{max})	-	-	100	μA
Quiescend current	-	-	1	μΑ

2.3.2 Low-voltage Linear Regulator

2.3.2 Low-voltage Linear Regulator					
Table 4 Switch-mode Regulator					
Normal Operation	Min	Тур.	Max	Unit	
Input voltage	0.65	-	1.35	V	
Output voltage	0.65	-	1.20	V	

2.3.3 Digital Terminals

Table 5 Digital Terminals						
	Min	Тур.	Max	Unit		
Input Voltage Levels	Input Voltage Levels					
V _{IL} input Logic level low	-0.4	-	0.4	V		
V_{H} input logic level high	0.7*VDD	-	VDD+0.4	V		
T _r /T _f	-	-	25	ns		
Output Voltage Levels						
V _{OL} output logic level low, I _{OL} = 4.0mA	-	-	0.4	V		
V _{OH} output logic level high, I _{OH} =-4.0mA	0.75*VDD	S	yst <u>err</u>	V		
T _f /T _f	1	H.C.	5	ns		
Input and Tristate Currents	coler					
With strong pull-up	-150	-40	-10	μΑ		
I ² C with strong pull-up	-250	-	-	μΑ		
With strong pull-down	10	40	150	μΑ		
With weak pull-up	-5.0	-1.0	-0.33	μΑ		
With weak pull-down	0.33	1.0	5.0	μΑ		
C _I input capacitance	1.0	-	5.0	pF		

C _I input capacitance	1.0	-	5.0	pF		
2.3.4 AIO Table 6 AIO						
Input Voltage Levels	Min	Тур.	Max	Unit		
Input voltage	0	-	1.3	V		



2.3.5 ESD Protection

Apply ESD static handling precautions during manufacturing. ESD handling maximum ratings are summarized in Table 7 below.

	Table 7	ESD	Handling	Maximum	Ratings
--	---------	-----	----------	---------	---------

Condition	Max	Unit
Human body model contact discharge per JEDEC EIA/JESD22-A114	2	2000V(all pins)
Machine model contact Discharge per JEDEC EIA/JESD22-A115	200V	200V(all pings)
Charged Device Model Contact Discharge per JEDEC EIA/JESD22-C101	111	500V(all pins)
2.4Current Consumption	ystem	

2.4Current Consumption

Operation Mode	Description	Average
Dormant	All functions are shutdown. To wake up toggle the wake pin.	5~6uA
Hibernate	VDD_PADS=ON, REFCLK=OFF, SLEEPCLK+ON, VDD_BAT=ON	5~6µА
Deep Sleep	VDD_PADS=ON, REFCLK=OFF, SLEEPCLK=ON, VDD_BAT=ON, RAM=ON, digital circuits=ON, SMPs=ON(low-power mode), 1ms wake-up time	7~8μA
Connected Standby	Solution	~1.2mA
RX/TX active		~ 4mA

Table 8 Current Consumption, Power supply 3.0v

2.5 Radio Characteristics

2.5.1 RF Ports

EcoSystem BlueSoleil i410e-S contains an integrated balun which provides a single-ended RF TX / RX port pin. No matching components are needed as the receive mode impedance is 50Ω and the transmitter has been optimized to deliver power in to a 50Ω load.



2.5.2 RF Receiver

The receiver features a near-zero IF architecture that allows the channel filters to be integrated onto the die. Sufficient out-of-band blocking specification at the LNA input allows the receiver to be used in close proximity to GSM and W-CDMA cellular phone transmitters without being significantly desensitized.

An ADC digitizes the IF received signa

Low Noise Amplifier

The LNA operates in differential mode and takes its input from the balanced port of the integrated balun.

RSSI Analogue to Digital Converter



The ADC samples the RSSI voltage on a packet-by-packet basis and implements a fast AGC. The front-end LNA gain is changed according to the measured RSSI value, keeping the first mixer input signal within a limited range. This improves the dynamic range of the receiver, improving performance in interference-limited environments.

2.5.3 RF Transmitter

IQ Modulator

The transmitter features a direct IQ modulator to minimize frequency drift during a transmit packet, which results in a controlled modulation index. Digital baseband transmit circuitry provides the required spectral shaping.

Power Amplifier

The internal PA has a maximum 7.5dBm output power without needing an external RF PA.

2.5.4 Bluetooth Radio Synthesizer

The Bluetooth radio synthesizer is fully integrated onto the die with no requirement for an external VCO screening, can varactor tuning diodes, LC resonators or loop filter. The synthesizer is guaranteed to lock in sufficient time across the guaranteed temperature range to meet Bluetooth uesolet v4.0 specification.

2.5.5 Baseband

Physical Layer Hardware Engine

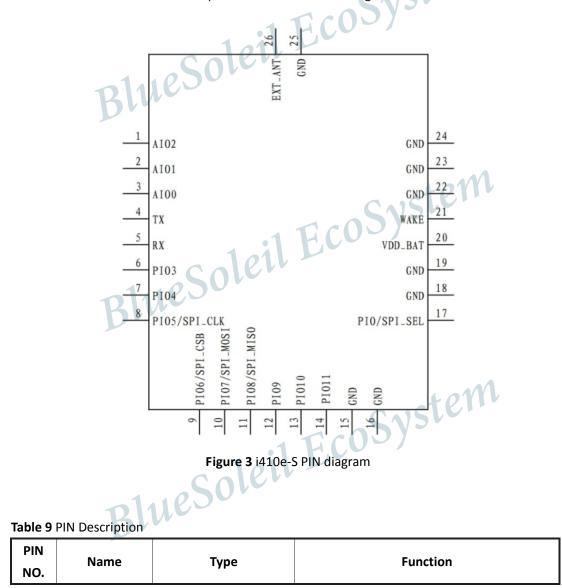


The hardware supports all optional and mandatory features of *Bluetooth* v4.0 specification. It performs the following features:

- Cyclic redundancy check •
- Encryption •
- Data whitening
- Access code correlation

auon aleil EcoSystem 314eSoleil **3 Pin Description**

BlueSoleil i410e-S's PIN descriptions are summarized in Figure 3 and Table 9 below.





1 AIO[2] Bidirectional Analogue programmable I/O line.	
analogue General-purpose analogue interface	pins.
2 AIO[1] Bidirectional Analogue programmable I/O line.	
analogue General-purpose analogue interface	pins.
3 AIO[0] Bidirectional Analogue programmable I/O line.	
analogue General-purpose analogue interface	pins.
4 TX CMOS Output CMOS output with weak internal pul	-up.
TXD is used to implement UART data	
transfer from i410e-S to another dev	ice.
5 RX CMOS Input CMOS Input CMOS input with weak internal pull-	down.
RXD is used to implement UART data	
transfer from another device to i410	e-S.
6 PIO3 Bidirectional with Programmable I/O line	
programmable strength internal	
strength internal	
pull-up/down	
7 PIO4 Bidirectional with Programmable I/O line	
programmable	
strength internal	
pull-up/down	
8 PIO5 / Bidirectional with Programmable I/O line or debug SPI	CLK
SPI_CLK programmable selected by SPI_EN#.	
strength internal CMOS input for the SPI clock signal w	vith
pull-up/down weak internal pull-down.	
9 PIO6 / Bidirectional with Programmable I/O line or debug SPI	CSB
SPI_CSB programmable selected by SPI_EN#.	
strength internal CMOS input with weak internal pull-	up.
pull-up/down Active low chip select for SPI	
10 PIO7 / D Bidirectional with Programmable I/O line or debug SPI	MOSI
SPI_MOSI programmable selected by SPI_EN#.	
strength internal SPI data input with weak internal	
pull-up/down pull-down.	
11PIO8 /Bidirectional withProgrammable I/O line or debug SPI	MISO
SPI_MISO programmable selected by SPI_EN#.	
strength internal SPI data output with weak internal	
pull-up/down pull-down.	
12 PIO9 Bidirectional with Programmable I/O line	
programmable	
strength internal	
pull-up/down	
13PIO10Bidirectional withProgrammable I/O line	



		strength internal			
		pull-up/down			
14	PIO11	Bidirectional with	Programmable I/O line		
		programmable			
		strength internal	oustern		
		pull-up/down	System		
15	GND	GND	Ground		
16	GND	GND	Ground		
17	PIO0/SPI_SEL	Input with strong	This pin foot pulls high to SPI mode, pulled		
	RU	internal pull-down	low for programmable I/O port mode.		
18	GND	GND	Ground		
19	GND	GND	Ground		
20	VDD_BAT	POWER	+3.3V supply voltage connection. Battery		
			input and regulator enables (active high).		
21	WAKE	WAKE	External wake-up function. When WAKE Pin		
		.1	pulls low(To Ground), it wakes up module.		
22	GND	GND	Ground		
23	GND	GND	Ground		
24	GND BU	GND	Ground		
25	EXT_ANT	External antenna	If use the external antenna interface, the		
			on-board antenna needs to be removed.		
26	GND	GND	Ground		

4.1UART Interface

BlueSoleil i410e-S Universal Asynchronous Receiver Transmitter (UART) interface provides a simple mechanism for communicating with other serial devices using the RS232 standard. The UART interface of i410e-S uses voltage levels of 0 to VDD and thus external transceiver IC is required to meet the voltage level specifications of UART.

In order to communicate with the UART at its maximum data rate using a standard PC, an accelerated serial port adapter card is required for the PC.

Table 10 Possible UART Settings

	Parameters	Possible Values		
Baud rate	Minimum	1200 baud (≤2%Error)		



		9600 baud (≤1%Error)		
	Maximum	2Mbaud (≤1%Error)		
Flow control		RTS/CTS, none		
Parity		None, Odd, Even		
Number of stop bi	ts	1 or 2		
Bits per channel	1.0	8		

NOTE: The maximum baud rate is 9600bps during deep sleep.

4.2SPI Interface Sole1

The synchronous serial port interface (SPI) is for interfacing with other digital devices. The SPI port can be used for system debugging. SPI interface is connected using the MOSI, MISO, CSB and CLK pins. It uses a 16-bit data and 16-bit address programming and debug interface. Transaction occurs when the internal processor is running or is stopped.

The module operates as a slave and receives commands on MOSI and outputs data on MISO. Table 11 shows the instruction cycle for a SPI transaction.

Table 11 Instruction Cycle for a SPI Transaction

Step	Operation	Description
1	Reset the SPI interface	Hold CSB high for 2 CLK cycles
2	Write the command word	Take CSB low and clock in the 8-bit command
3	Write the address	Clock in the 16-bit address word
4	Write or read data words	Clock in or out 16-bit data words
5	Termination	Take CSB high

With the exception of reset, CSB must be held low during the transaction. Data on MOSI is clocked on the rising edge of the clock line CLK. When reading, i410e-S replies to the master on MISO with the data changing on the falling edge of the CLK. The master provides the clock on CLK. The transaction is terminated by taking CSB high.

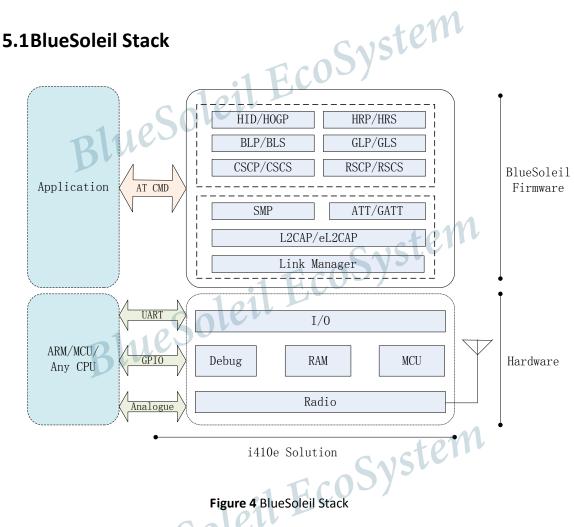
The auto increment operation on the i410e-S cuts down on the overhead of sending a command word and the address of a register for each read or write, especially when large amounts of data are to be transferred. The auto increment offers increased data transfer efficiency on the i410e-S. To invoke auto increment, CSB is kept low, which auto increments the address, while providing an extra 16 clock cycles for each extra word written or read.

5 Software Stacks

BlueSoleil i410e-S is supplied with *Bluetooth* v4.0 compliant stack firmware, which runs on



the internal RISC microcontroller. The i410e-S software architecture allows *Bluetooth* processing and the application program to be shared in different ways between the internal RISC microcontroller and an external host processor (if any).



As illustrated in Figure 4 above, no host processor is required to run the *Bluetooth* protocol stack. All BlueSoleil stack layers, including application software, run on the internal RISC processor.

The MCU interfaces to BlueSoleil i410e-S via one or more of the physical interfaces, which are also shown in the figure 4. The most common interfacing is done via UART interface using the ASCII commands supported by the BlueSoleil stack. With these ASCII commands the user can access *Bluetooth* functionality without paying any attention to the complexity, which lies in the *Bluetooth* protocol stack.

The user may write applications code to run on the MCU to control BlueSoleil stack with ASCII commands and to develop *Bluetooth* powered applications. Please refer to BlueSoleil_i410e_Programming_Manual.pdf.



6 Re-flow Temperature-time Profile

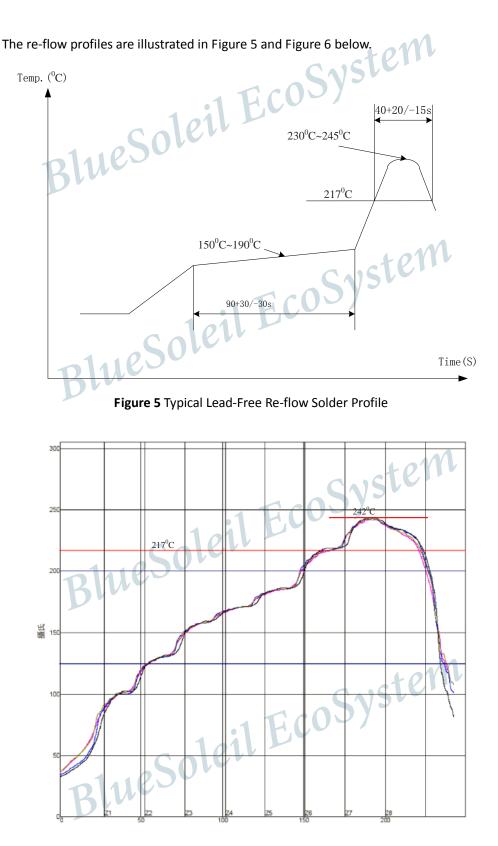


Figure 6 Typical Lead-free Re-flow



The soldering profile depends on various parameters according to the use of different solder and material. The data here is given only for guidance on solder re-flow.

i410e-S will withstand up to two re-flows to a maximum temperature of 245°C.

7 Reliability and Environmental Specification

7.1Temperature test

Put the module in demo board which uses exit power supply, power on the module and connect to mobile. Then put the demo in the -40 $^{\circ}$ C space for 1 hour and then move to +85 $^{\circ}$ C space within 1 minute, after 1 hour move back to -40 $^{\circ}$ C space within1 minute. This is 1 cycle. The cycles are 32 times and the units have to pass the testing.

7.2Vibration Test

The module is being tested without package. The displacement requests 1.5mm and sample is vibrated in three directions(X,Y,Z).Vibration frequency set as 0.5G, a sweep rate of 0.1 octave/min from 5Hz to 100Hz last for 90 minutes each direction. Vibration frequency set as 1.5G, a sweep rate of 0.25 octave/min from 100Hz to 500Hz last for 20 minutes each direction.

7.3Desquamation Test

Use clamp to fix the module, measure the pull of the component in the module, make sure the module's soldering is good.

7.4Drop Test

Free fall the module (condition built in a wrapper which can defend ESD) from 150cm height to cement ground, each side twice, total twelve times. The appearance will not be damaged and all functions OK.

7.5Packaging Information

After unpacking, the module should be stored in environment as follows:

stem



- Temperature: 25 °C ± 2 °C
- Humidity: <60%
- No acidity, sulfur or chlorine environment

The module must be used in four days after unpacking. System

8 Layout and Soldering Considerations

8.1Soldering Recommendations

BlueSoleil i410e-S is compatible with industrial standard reflow profile for Pb-free solders. The reflow profile used is dependent on the thermal mass of the entire populated PCB, heat transfer efficiency of the oven and particular type of solder paste used. Consult the datasheet of particular solder paste for profile configurations.

IVT Corporation will give following recommendations for soldering the module to ensure reliable solder joint and operation of the module after soldering. Since the profile used is process and layout dependent, the optimum profile should be studied case by case. Thus following recommendation should be taken as a starting point guide. coSystem

8.2Layout Guidelines

It is strongly recommended to use good layout practices to ensure proper operation of the module. Placing copper or any metal near antenna deteriorates its operation by having effect on the matching properties. Metal shield around the antenna will prevent the radiation and thus metal case should not be used with the module. Use grounding via separated max 3 mm apart at the edge of grounding areas to prevent RF penetrating inside the PCB and causing an unintentional resonator. Use GND via all around the PCB edges.

The mother board should have no bare conductors or via in this restricted area, because it is not covered by stop mask print. Also no copper (planes, traces or via) are allowed in this area, BlueSolell because of mismatching the on-board antenna.



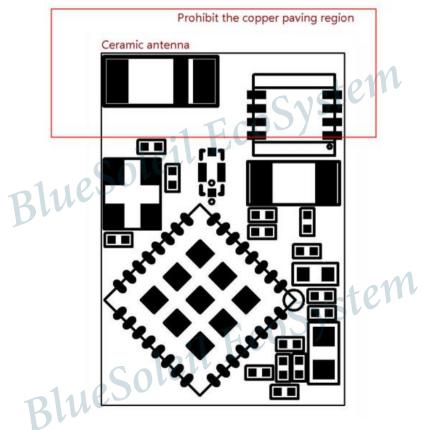


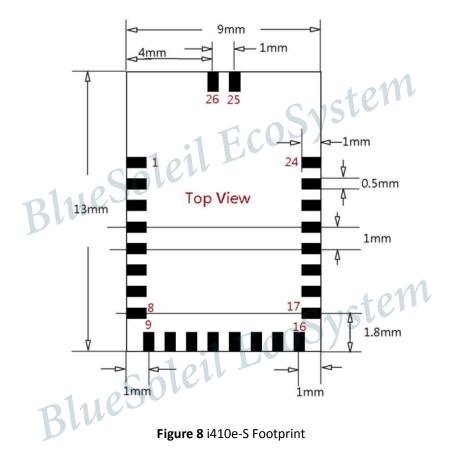
Figure 7 i410e-S Restricted Area

Following recommendations helps to avoid EMC problems arising in the design. Note that each design is unique and the following list do not consider all basic design rules such as avoiding capacitive coupling between signal lines. Following list is aimed to avoid EMC problems caused by RF part of the module. Use good consideration to avoid problems arising from digital signals in the design.

Ensure that signal lines have return paths as short as possible. For example if a signal goes to an inner layer through a via, always use ground via around it. Locate them tightly and symmetrically around the signal via. Routing of any sensitive signals should be done in the inner layers of the PCB. Sensitive traces should have a ground area above and under the line. If this is not possible, make sure that the return path is short by other means (for example using a ground 9 Physical Dimensions Rules Blues

BlueSoleil i410e-S's dimension is 13mm (L) *9mm (W).





10

TBD

Certification 11

11.1 Bluetooth

BlueSoleil i410e module is qualified as a Bluetooth controller subsystem and it fulfills all the mandatory requirements of Bluetooth 4.0 core specification. If not modified in any way, it is a complete Bluetooth entity, containing software and hardware functionality as well as the whole RF-part including the antenna. This practically translates to that if the module is used without modification of any kind, it does not need any Bluetooth approval work for evaluation on what needs to be tested.

i410e Qualified Design ID (QDID): B020729



11.2 CE 0700

€€ 0700

11.3 FCC

Hereby, IVT Corporation declares that this device is in compliance with the essential Juesoleil Ecosys requirements and other relevant provisions of Directive 1999/5/EC

S78-IVTI410E FCC IDENTIFIER: Name of Grantee: IVT Corporation Equipment Class: Digital Transmission System Notes: Bluetooth module 4.0 LE Single Modular Modular Type:

11.4 IC

CERTIFICATION NUMBER: IC: 11004A-IVTI410E

Issued to/Délivré a: IVT Corporation 5/F, Zhongguancun Fazhan Building No. 12, Address: Shangdi Xinxi Road, Haidian District, Beijing

slue

Date Issued: 7/8/2013

Original Nature of Application/Nature d'Application: Equipment Description/Genre de Matériel: BT module 4.0 LE Low Power Device (2400-2483.5 MHz), Modular Approval Equipment Category/Catégorie de Matériel: Category I

i410e

Bluetooth Technology Best Developed 12 EcoSyster

Corporation

Type of Radio Equipment:

Model Number(s)/Modele

IVT Corporation is one of Bluetooth technology BEST developed together which is authenticated by The Bluetooth SIG. See Figure 9 below.



Thank	s to those th	hat helped brin	a to completion	Bluetocth Core	ST DEVE Specification Add offerv1.4, AVV Co	dendum 1. He	alth Device Pr	ošia v1.0.
	and				WT Mucu	Company Contraction	Quelcown se	mane symbus
Anritsu	MIUU A	IECHNUL molece		Anywhere	ED TOGET	HEK Burno	oth Core Specific	Microsoft
	NOKIA	Prant.	QUALCOWAR 4	S socket	STACCAT	SONY	Stricsson	TEXAS INSTRUMENTS

Figure 9 IVT is one of *Bluetooth* technology BEST developed together

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